



Community Member Monthly Highlights – September – October 5, 2022

Community Member Monthly Highlights – September

[From Different Dimensions](#)

Oct 05, 2022 · By Trine Pierik · [Ajinomoto](#), [ASE](#), [Brewer Science](#), [CyberOptics](#), [ERS](#), [EV Group](#), [Evatec](#), [Henkel](#), [KLA](#), [Lam Research](#), [LPKF](#), [Mercury Systems](#), [Micross](#), [Mosaic Microsystems](#), [MRSI](#), [siemens](#), [StratEdge Corporation](#), [SurplusGLOBAL](#), [Veeco](#)



SEPTEMBER

MEMBER HIGHLIGHTS

Welcome to our new monthly community member news in review where we will highlight community news, events, milestones, anything worth sharing from the month previous. If we missed you this month, be sure to add us to your distribution list, we don't want to leave anyone out. Our community members are active industry participants and it's our goal to share all that we can.

The **Ajinomoto Group** released its 2022 ASV report that shows how ASV is being utilized across all Group business units. The company's dedication to providing economic and social value through the organization's business activities is presented through this value exchange, called the Ajinomoto Group Creating Shared Value (ASV). The report contains an aspirational message and commitments from the President and CEO, Taro Fujie, highlights initiatives from across the Ajinomoto Group and much more. **ASE's** Dr. Bradford Factor presented at the SEMI Europe MEMS & Image Sensor Summit explaining that innovative packaging solutions are compelling given rising demand for MEMS and sensors integration to enable a wide spectrum of applications, including smartphones, wearable, automotive, high performance computing, AI, industry 4.0 and much more.

Dr Bill Chen, **ASE** Fellow and HIR Chairperson, delivered a thought-provoking presentation on the growing importance of semiconductors as a foundational pillar to a nation's economy at the Heterogeneous Integration Global Summit during SEMICON Taiwan. He discussed how to take full

advantage of unique opportunities for advancing science & technology to create a better world, emphasizing that HI collaboration is key to addressing challenges and realizing the vision of the future. **Brewer Science** will host "Manufacturing Day 2022," on October 7th, which will feature an open house and guided tours of its Vichy, MO high-volume manufacturing facility.

Dr. Alvin Lee, Regional Director at **Brewer Science** presented new developments in temporary and permanent bonding material technologies for advanced packaging at the SEMICON Taiwan Heterogeneous Integration Global Summit. His presentation, *New Developments in Temporary and Permanent Bonding Material Technologies for Advanced Packaging*, addressed cost-effective solutions and innovative material technologies that enable advanced wafer-level packaging applications. **CyberOptics** unveiled a new teaching system for semiconductor applications at SPIE Photomask Technology and EUV Lithography in Minneapolis, Minnesota. The new ReticleSense® Auto Teaching System™ (ATSR™) is a multi camera sensor used with CyberSpectrum™ software to teach accurate reticle hand-off calibration for proper alignment and set-up of semiconductor tools.

Jeff Bertelsen, VP of Finance, CFO, COO and Secretary of **CyberOptics**, was selected for a 2022 CFO of the Year Award by the Minneapolis / St. Paul Business Journal.

ERS electronic's Next-Gen Thermal Chuck System AC3 Fusion has been nominated by the World Electronic Achievements in the category "Test & Measurement." Voting is still open.

Roland Rettenmeier represented **Evatec** at the Fraunhofer Panel Level Packaging Consortia and Symposium, discussing the PLC outcome and presenting Evatec's State of the Art Thin Film Solutions for Wafer Level Packaging and Panel Level Packaging.

EV Group (EVG) announced that it has expanded its collaboration with the Industrial Technology Research Institute (ITRI), one of the world's leading applied technology research institutes based in Hsinchu, Taiwan, on developing advanced heterogeneous integration processes.

EVG introduced NanoCleave™, a revolutionary layer release technology for silicon that enables ultra-thin layer stacking for front-end processing, including advanced logic, memory and power device formation, as well as semiconductor advanced packaging. NanoCleave is a fully front-end-compatible layer release technology that features an infrared (IR) laser that can pass through silicon, which is transparent to the IR laser wavelength.

Henkel announced the commercialization of its latest semiconductor-grade capillary underfill (CUF) formulation for advanced packaging applications. The material, Loctite EccobondUF 9000AG, enables advanced silicon (Si) node flip chip integration by providing robust interconnect protection and compatibility with high-volume manufacturing environments.

KLA Corporation announced plans to build a new research-and-development (R&D) and manufacturing center for the SPTS division, in Newport, Wales, UK. The new development designed to meet BREEAM standard of sustainability rating of excellent is expected to include a capital investment of more than \$100 million and create a 200,000 square foot facility.

Lam Research opened a Center for Engineering in Bengaluru. The new lab will focus on R&D, engineering, and testing of wafer fabrication hardware and software for next-generation DRAM, NAND, and logic technologies.

On September 28, **LPKF Laser & Electronics** welcomed institutional investors and analysts at its headquarters in Garbsen for its Capital Markets Day 2022. The Management Board and Senior Management presented the Big Picture of LPKF including current business and strategic priorities.

Mercury Systems introduced the Model 5560, its next-generation 3U OpenVPX™ SOSA™ aligned co-processing board that is the first to be powered by the AMD Xilinx Versal® HBM series with integrated high-bandwidth memory.

Micross achieved the rigorous ISO/IEC 17025:2017 certification, which includes AS6171, the most comprehensive standard for counterfeit mitigation. This standard ensures heightened consistency across the supply chain for test techniques and requirements based on assessed risk associated with the application, component, supplier, and other relevant risk factors.

MRSI Systems (Mycronic Group) introduced the MRSI-HVM1 and MRSI-H1 die bonders with 1µm machine accuracy and provide ideal solutions for the increasingly demanding applications such as mass manufacturing of silicon photonics and LIDAR. The MRSI-H1 and MRSI-HVM1 will be available in the Q4, 2022.

Siemens Digital Industries Software introduced the Tessent™ Multi-die software solution, which helps customers dramatically speed and simplify critical design-for-test (DFT) tasks for next-generation integrated circuits (ICs) based on 2.5D and 3D architectures.

StratEdge Corporation announced assembly services for attaching gallium nitride (GaN) and other high-frequency, high-power devices using gold-tin (AuSn) and gold-silicon (AuSi) onto copper-molybdenum-copper (CMC) tabs. StratEdge's proprietary eutectic die attach method maximizes the power output a chip can achieve, optimizing its performance and providing an efficient way to dissipate heat to avoid overheating and failures during normal operation.

SurplusGLOBAL celebrated its 10th Anniversary of the Smiletogether Foundation established to support families with developmental disabilities.

Veeco's D&I Council sponsored an event with Swarthmore College and the Society of Hispanic Engineers (SHPE) organization in honor of Hispanic Heritage Month. Process Development Engineers, Kevin Donnelly and Joel Bahena discussed the semiconductor industry and outlined Veeco's role in several of its key technologies that shape the future.

Who's Hiring?

TEL <https://tel.wd3.myworkdayjobs.com/en-US/TEL-Careers/introduceYourself>

ERS <https://www.ers-gmbh.com/career-2>

Mosaic <https://www.mosaicmicro.com/wp-content/uploads/VP-BusDes-Mosaic-2022-04-28.pdf>

<https://www.3dincites.com/2022/10/community-member-monthly-highlights-september/>